Technical specifications	Hybrid 5	Hybrid 3	
Maximum output per hour	165 k (121k IPC 9850A)	99 k (79k IPC 9850A)	
Maximum output per hour for flip chip bonding (IPC 9850)	10.5 - 16 k with dipping 13.5 - 27 k without dipping	10.5 - 16 k with dipping 13.5 - 27 k without dipping	
Placement quality	< 1 dpm	< 1 dpm	
Placement accuracy @ CpK1	25 µm for passives 18 µm for QFP/BGA/FC 7 µm for flip chips[1]	25 µm for passives 18 µm for QFP/BGA/FC 7 µm for flip chips[1]	CPR/SPR SPR/TPR TPR
Minimum component size (LxW):	0.25 x 0.125 mm (0201m)	0.25 x 0.125 mm (0201m)	
Maximum component size (LxW):	45 x 45 mm (1.77 x 1.77”)	45 x 45 mm (1.77 x 1.77”)	
Maximum component height: - Optional	10.5 mm (0.41”) 12 mm (0.47”)	10.5 mm (0.41”) 12 mm (0.47”)	
Placement force range	0.5 to 8 N	0.5 to 8 N	
Maximum board size (LxW): - Standard - Optional	 515 x 390 mm (20.28 x 15.35”) 800 x 457 mm (31.5 x 18”)	 475 x 390 mm (18.7 x 15.35”) 800 x 457 mm (31.5 x 18”)	
Minimum board size (LxW): - Standard - Optional	 50 x 50 mm (2 x 2”) 50 x 25 mm (2 x 1”)	 50 x 50 mm (2 x 2”) 50 x 25 mm (2 x 1”)	
Maximum optional board length	800 mm (31.5”)	800 mm (31.5”)	
Maximum optional board width	543 mm (21.4”)	543 mm (21.4”)	
Board thickness: - Standard - Optional	 0.3 to 6 mm (0.01 to 0.24”) ≥ 0.05 mm	 0.3 to 6 mm (0.01 to 0.24”) ≥ 0.05 mm	
Automatic toolbit exchange	Nozzles	Nozzles	
Maximum tape feeding positions (8mm): Single lane feeders Twin tape feeders	 130 260	 76 156	
Feeding options (special feeders on request)	Tape, waffle pack, tray, wafer, others	Tape, waffle pack, tray, wafer, others	
Footprint excl. feeders (LxW)	3,720 x 1,705 mm (146.46 x 67.13”)	2,760 x 1,705 mm (108.66 x 67.13”)	

[1] Based on K&S Metrology @ 3 sigma

For extended specifications, not specified in these tables, please call your local Kulicke & Soffa contact.

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